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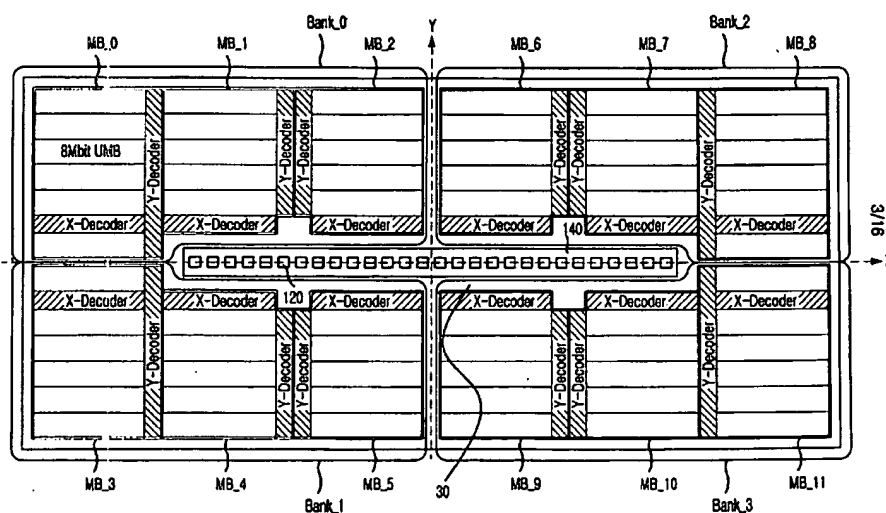
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(54) Title: MEMORY CHIP ARCHITECTURE HAVING NON-RECTANGULAR MEMORY BANKS AND METHOD FOR ADDRESSING MEMORY BANKS



(57) Abstract: A semiconductor memory device having semiconductor memory chips, each semiconductor memory chip includes a plurality of memory banks capable of independently to be accessed, each memory bank having a plurality of memory blocks, wherein at least two memory banks, which are neighbored each other in the same memory bank, have the different number of unit memory blocks, so that each bank has a non-rectangular shape.

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